MEPNN Supplier Scouting Opportunity Synopsis

Section 1: General Information

Scouting Number	2025-086
Item to be Scouted	Multi layered custom circuit boards
Days to be scouted	60
Response Due By	05/19/2025
Description	Multi layered custom circuit boards to be used as the basis for a manufactured circuit board assembly.
Notify Requester Immediately	
State item to be used in	Ohio

Section 2: Technical Information

Type of supplier being sought	Manufacturer
Reason	Re-shore
Describe the manufacturing processes (elaborate to provide as much detail as possible)	Includes but is not limited to designing, etching, lamination, drilling and plating, imaging and etching, silkscreen printing, and finishing.
Provide dimensions / size / tolerances / performance specifications for the item	11" x 4.25" x 1.5mm Additional information and specifications will be shared with potential manufacturers once we have a Non-disclosure Agreement (NDA) in place.
List required materials needed to make the product, including materials of product components	Includes but is not limited to fiberglass-reinforced epoxy resin, or other insulating materials, copper, solder mask, solder, adhesives, plating materials and various electronic components.
Are there applicable certification requirements?	No
Are there applicable regulations?	No
Are there any other stndards, requirements, etc.?	No
NAICS 1	334412 Bare printed circuit board manufacturing
NAICS 2	334418 Printed circuit assembly (electronic assembly) manufacturing
Additional Technical Comments	

Section 4: Business Information

Estimated potential business volume	500/wk, 25,000/yr
Estimated target price / unit cost information (if unavailable explain)	$4
When is it needed by?	ASAP, but no specific date.
Describe packaging requirements	Best available. Delivered undamaged. Specifics discussed in negotiation.
Where will this item be shipped?	Akron, OH

Additional Comments

Is there other information you would like to include?	